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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

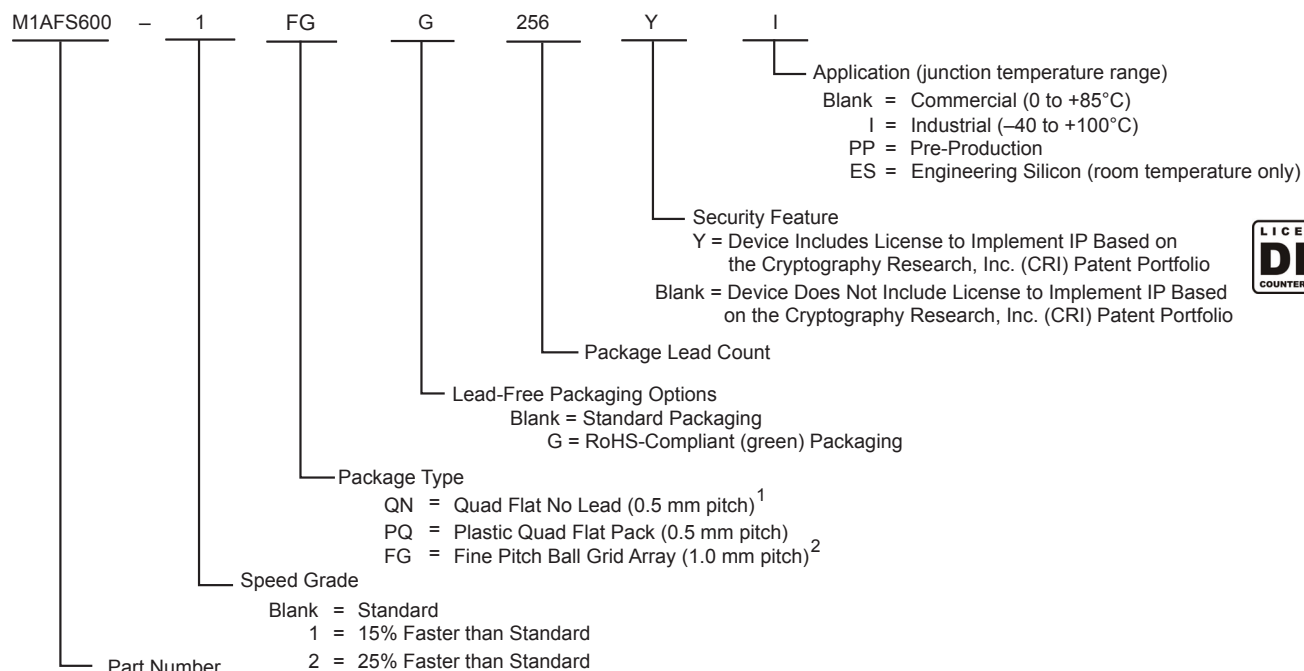
Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	-
Total RAM Bits	27648
Number of I/O	60
Number of Gates	90000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	180-WFQFN Dual Rows, Exposed Pad
Supplier Device Package	180-QFN (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microsemi/afs090-qng180i

Product Ordering Codes



Fusion Devices

AFS090 = 90,000 System Gates
AFS250 = 250,000 System Gates
AFS600 = 600,000 System Gates
AFS1500 = 1,500,000 System Gates

ARM-Enabled Fusion Devices

M1AFS250 = 250,000 System Gates
M1AFS600 = 600,000 System Gates
M1AFS1500 = 1,500,000 System Gates

Pigeon Point Devices

P1AFS600 = 600,000 System Gates
P1AFS1500 = 1,500,000 System Gates

MicroBlade Devices

U1AFS250 = 250,000 System Gates
U1AFS600 = 600,000 System Gates
U1AFS1500 = 1,500,000 System Gates

Notes:

- For Fusion devices, Quad Flat No Lead packages are only offered as RoHS compliant, QNG packages.
- MicroBlade and Pigeon Point devices only support FG packages.

Fusion Device Status

Fusion	Status	Cortex-M1	Status	Pigeon Point	Status	MicroBlade	Status
AFS090	Production						
AFS250	Production	M1AFS250	Production			U1AFS250	Production
AFS600	Production	M1AFS600	Production	P1AFS600	Production	U1AFS600	Production
AFS1500	Production	M1AFS1500	Production	P1AFS1500	Production	U1AFS1500	Production

VersaTile Characteristics

Sample VersaTile Specifications—Combinatorial Module

The Fusion library offers all combinations of LUT-3 combinatorial functions. In this section, timing characteristics are presented for a sample of the library (Figure 2-3). For more details, refer to the *IGLOO*, *ProASIC3*, *SmartFusion*, and *Fusion Macro Library Guide*.

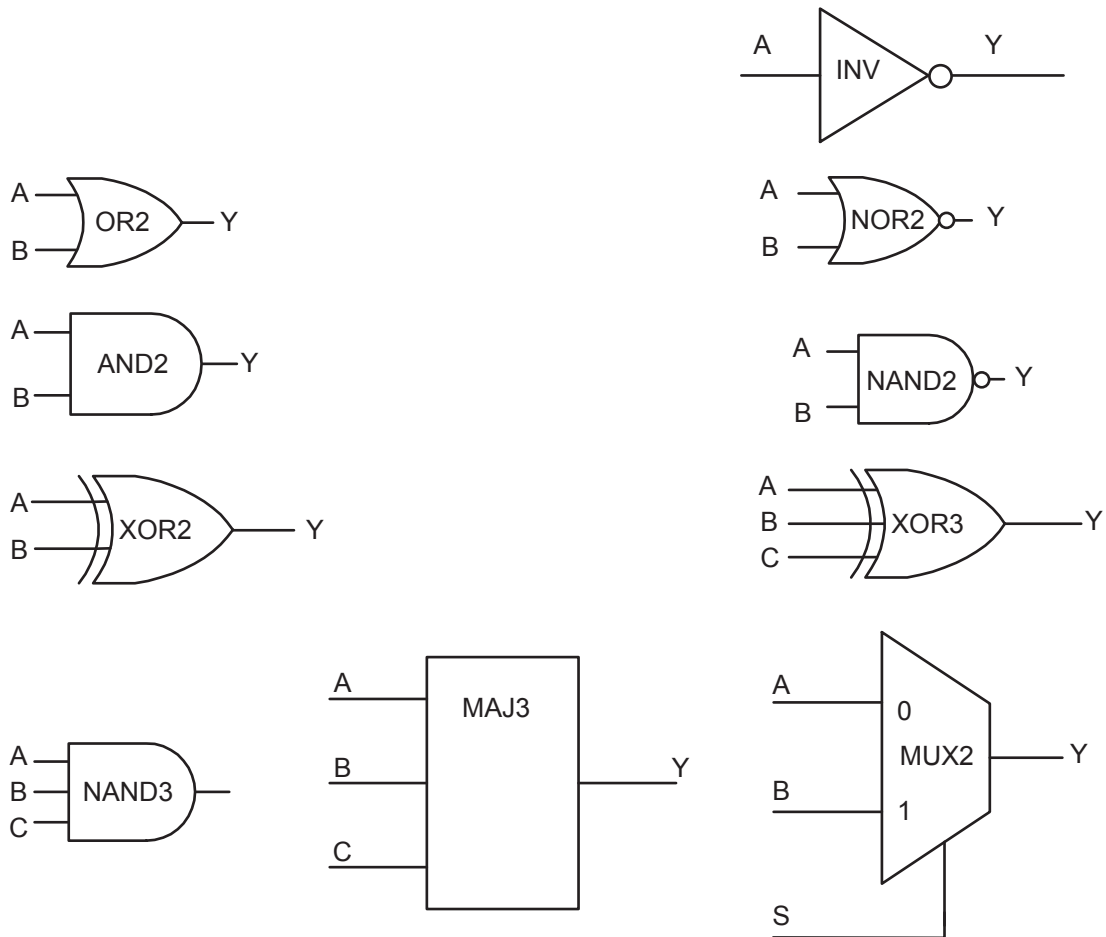


Figure 2-3 • Sample of Combinatorial Cells

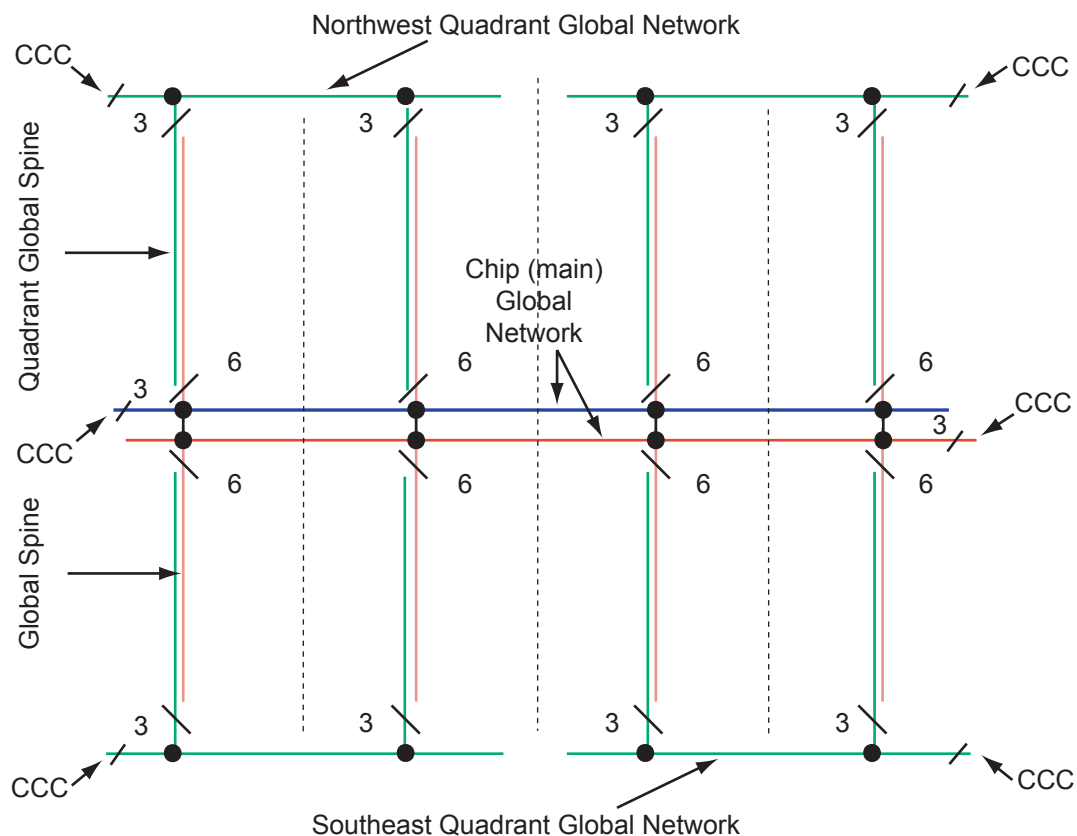


Figure 2-12 • Global Network Architecture

Table 2-4 • Globals/Spines/Rows by Device

	AFS090	AFS250	AFS600	AFS1500
Global VersaNets (trees)*	9	9	9	9
VersaNet Spines/Tree	4	8	12	20
Total Spines	36	72	108	180
VersaTiles in Each Top or Bottom Spine	384	768	1,152	1,920
Total VersaTiles	2,304	6,144	13,824	38,400

Note: *There are six chip (main) globals and three globals per quadrant.

Clock Aggregation

Clock aggregation allows for multi-spine clock domains. A MUX tree provides the necessary flexibility to allow long lines or I/Os to access domains of one, two, or four global spines. Signal access to the clock aggregation system is achieved through long-line resources in the central rib, and also through local resources in the north and south ribs, allowing I/Os to feed directly into the clock system. As [Figure 2-14](#) indicates, this access system is contiguous.

There is no break in the middle of the chip for north and south I/O VersaNet access. This is different from the quadrant clocks, located in these ribs, which only reach the middle of the rib. Refer to the [Using Global Resources in Actel Fusion Devices](#) application note.

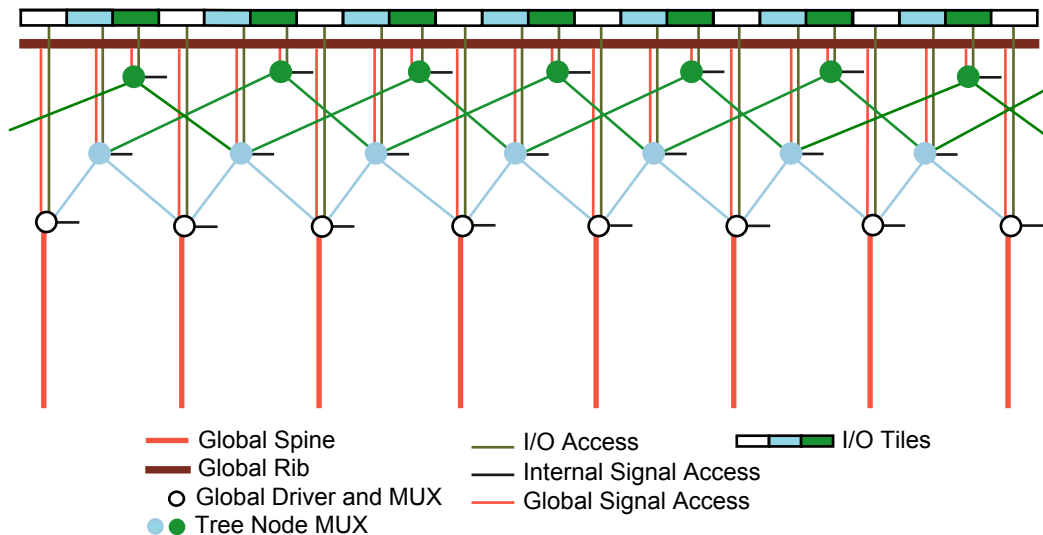


Figure 2-14 • Clock Aggregation Tree Architecture

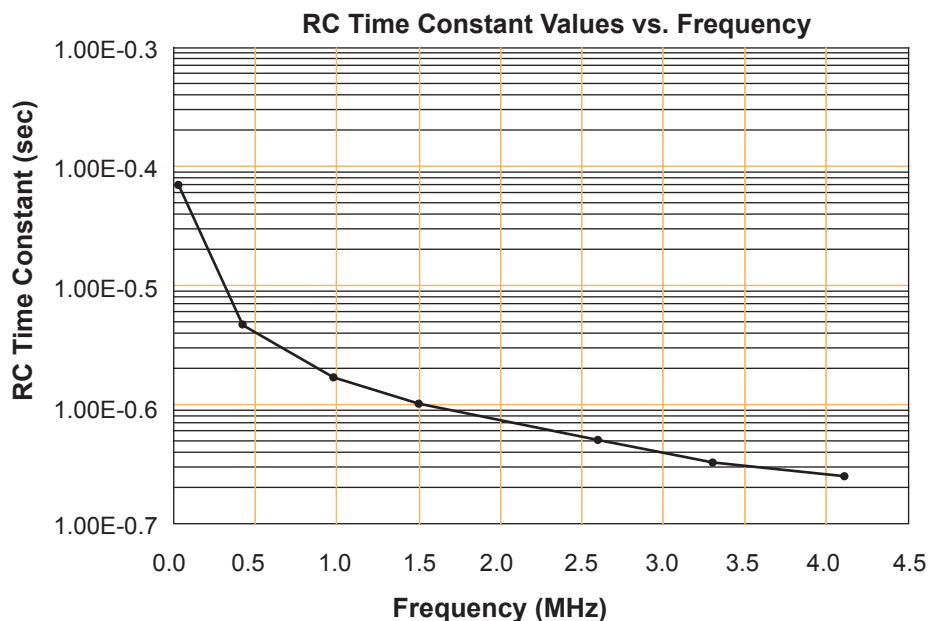
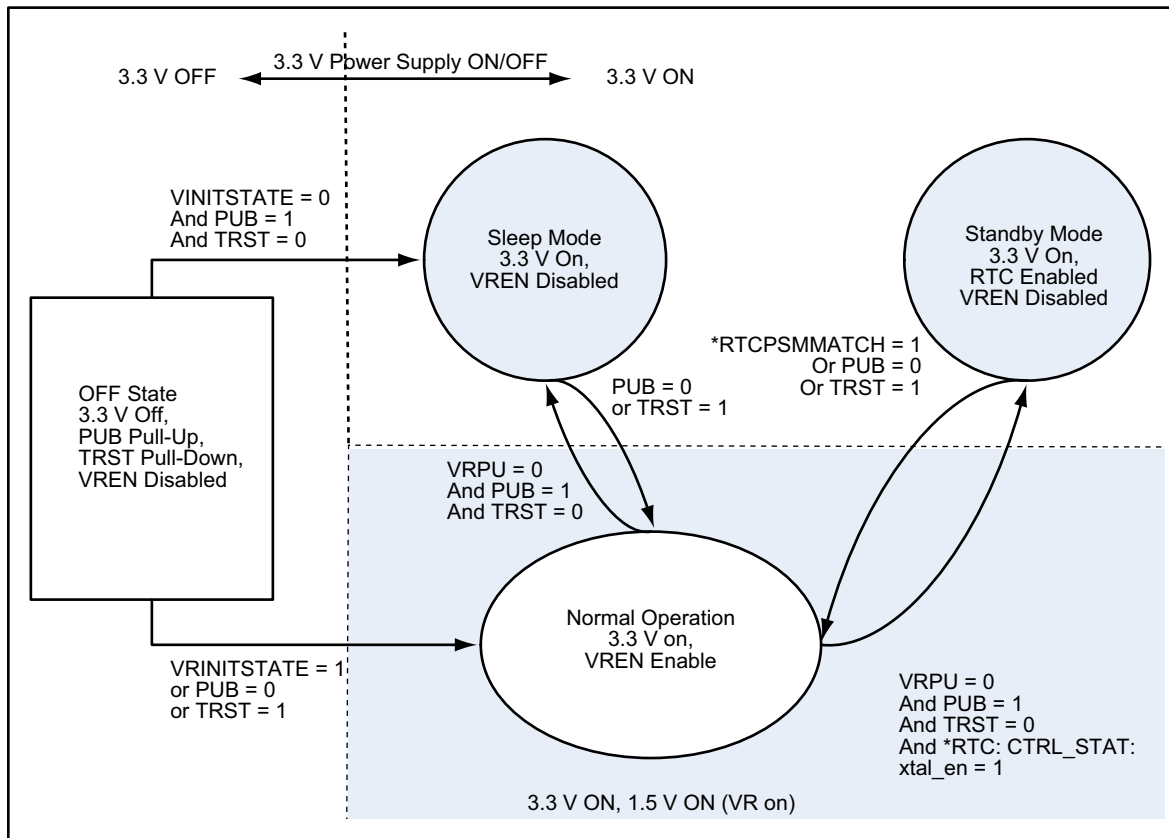


Figure 2-18 • Crystal Oscillator: RC Time Constant Values vs. Frequency (typical)

Table 2-10 • XTLOSC Signals Descriptions

Signal Name	Width	Direction	Function		
XTL_EN*	1		Enables the crystal. Active high.		
XTL_MODE*	2		Settings for the crystal clock for different frequency.		
			Value	Modes	Frequency Range
			b'00	RC network	32 KHz to 4 MHz
			b'01	Low gain	32 to 200 KHz
			b'10	Medium gain	0.20 to 2.0 MHz
			b'11	High gain	2.0 to 20.0 MHz
SELMODE	1	IN	Selects the source of XTL_MODE and also enables the XTL_EN. Connect from RTCXTLSEL from AB.		
			0	For normal operation or sleep mode, XTL_EN depends on FPGA_EN, XTL_MODE depends on MODE	
			1	For Standby mode, XTL_EN is enabled, XTL_MODE depends on RTC_MODE	
RTC_MODE[1:0]	2	IN	Settings for the crystal clock for different frequency ranges. XTL_MODE uses RTC_MODE when SELMODE is '1'.		
MODE[1:0]	2	IN	Settings for the crystal clock for different frequency ranges. XTL_MODE uses MODE when SELMODE is '0'. In Standby, MODE inputs will be 0's.		
FPGA_EN*	1	IN	0 when 1.5 V is not present for VCC 1 when 1.5 V is present for VCC		
XTL	1	IN	Crystal Clock source		
CLKOUT	1	OUT	Crystal Clock output		

Note: *Internal signal—does not exist in macro.



Note: * To enter and exit standby mode without any external stimulus on *PUB* or *TRST*, the *vr_en_mat* in the *CTRL_STAT* register must also be set to 1, so that *RTCPSMMATCH* will assert when a match occurs; hence the device exits standby mode.

Figure 2-31 • State Diagram for All Different Power Modes

When *TRST* is 1 or *PUB* is 0, the 1.5 V voltage regulator is always ON, putting the Fusion device in normal operation at all times. Therefore, when the JTAG port is not in reset, the Fusion device cannot enter sleep mode or standby mode.

To enter standby mode, the Fusion device must first power-up into normal operation. The RTC is enabled through the RTC Control/Status Register described in the ["Real-Time Counter \(part of AB macro\)" section on page 2-33](#). A match value corresponding to the wake-up time is loaded into the Match Register. The 1.5 V voltage regulator is disabled by setting *VRPU* to 0 to allow the Fusion device to enter standby mode, when the 1.5 V supply is off but the RTC remains on.

SRAM Characteristics

Timing Waveforms

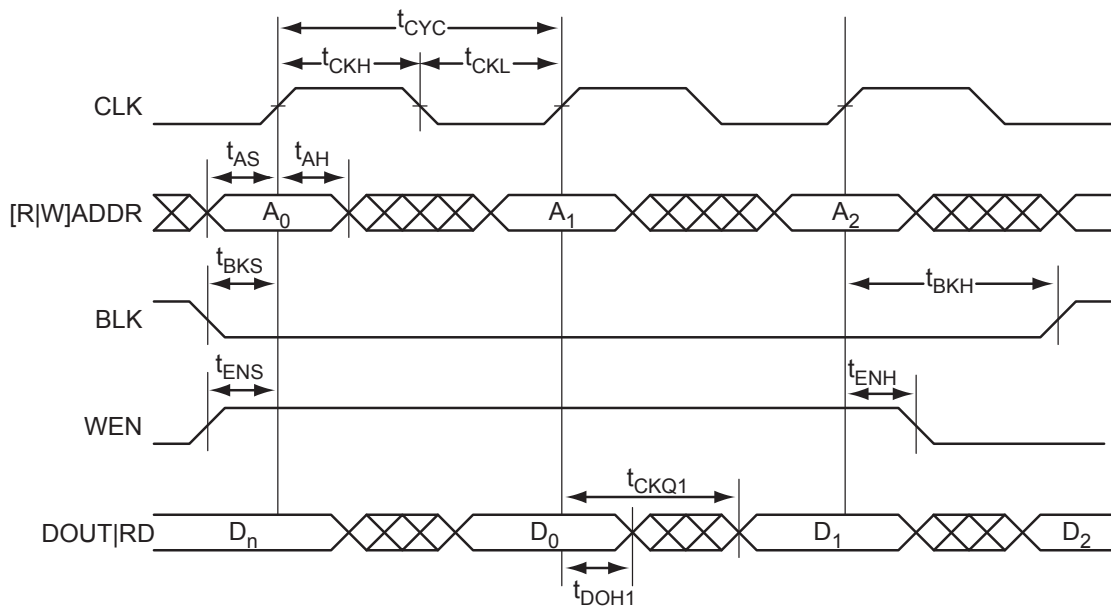


Figure 2-50 • RAM Read for Flow-Through Output. Applicable to both RAM4K9 and RAM512x18.

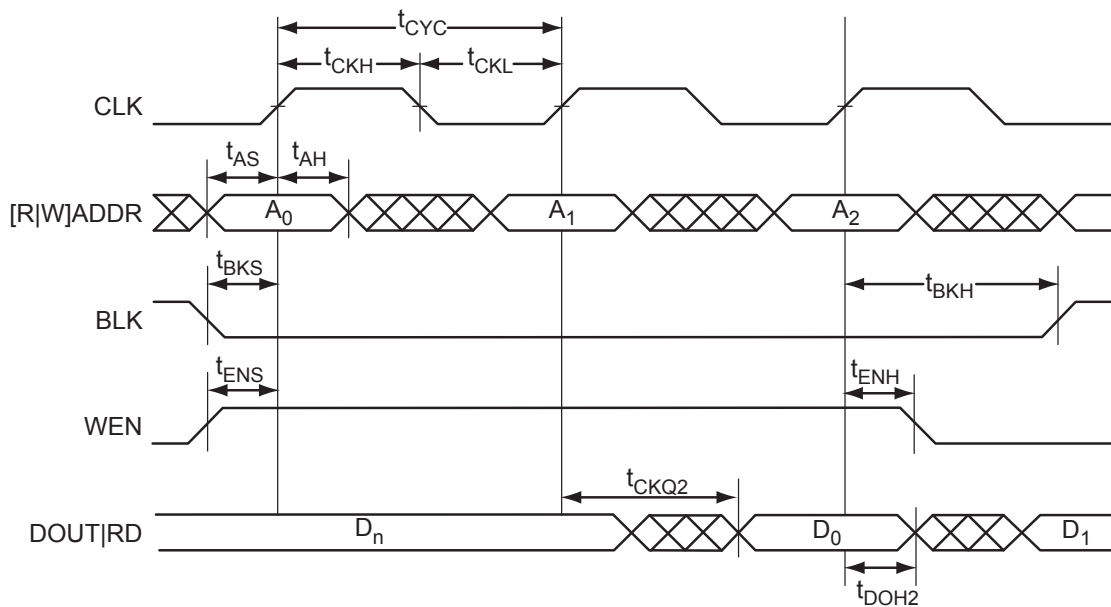


Figure 2-51 • RAM Read for Pipelined Output. Applicable to both RAM4K9 and RAM512x18.

Timing Characteristics

Table 2-35 • FIFO

Commercial Temperature Range Conditions: $T_J = 70^{\circ}\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$

Parameter	Description	–2	–1	Std.	Units
t_{ENS}	REN, WEN Setup time	1.34	1.52	1.79	ns
t_{ENH}	REN, WEN Hold time	0.00	0.00	0.00	ns
t_{BKS}	BLK Setup time	0.19	0.22	0.26	ns
t_{BKH}	BLK Hold time	0.00	0.00	0.00	ns
t_{DS}	Input data (WD) Setup time	0.18	0.21	0.25	ns
t_{DH}	Input data (WD) Hold time	0.00	0.00	0.00	ns
t_{CKQ1}	Clock High to New Data Valid on RD (flow-through)	2.17	2.47	2.90	ns
t_{CKQ2}	Clock High to New Data Valid on RD (pipelined)	0.94	1.07	1.26	ns
t_{RCKEF}	RCLK High to Empty Flag Valid	1.72	1.96	2.30	ns
t_{WCKFF}	WCLK High to Full Flag Valid	1.63	1.86	2.18	ns
t_{CKAF}	Clock High to Almost Empty/Full Flag Valid	6.19	7.05	8.29	ns
t_{RSTFG}	RESET Low to Empty/Full Flag Valid	1.69	1.93	2.27	ns
t_{RSTAF}	RESET Low to Almost-Empty/Full Flag Valid	6.13	6.98	8.20	ns
t_{RSTBQ}	RESET Low to Data out Low on RD (flow-through)	0.92	1.05	1.23	ns
	RESET Low to Data out Low on RD (pipelined)	0.92	1.05	1.23	ns
$t_{REMRSTB}$	RESET Removal	0.29	0.33	0.38	ns
$t_{RECRSTB}$	RESET Recovery	1.50	1.71	2.01	ns
$t_{MPWRSTB}$	RESET Minimum Pulse Width	0.21	0.24	0.29	ns
t_{CYC}	Clock Cycle time	3.23	3.68	4.32	ns
F_{MAX}	Maximum Frequency for FIFO	310	272	231	ns

Note: For the derating values at specific junction temperature and voltage supply levels, refer to [Table 3-7](#) on [page 3-9](#).

Channel Input Offset Error

Channel Offset error is measured as the input voltage that causes the transition from zero to a count of one. An Ideal Prescaler will have offset equal to $\frac{1}{2}$ of LSB voltage. Offset error is a positive or negative when the first transition point is higher or lower than ideal. Offset error is expressed in LSB or input voltage.

Total Channel Error

Total Channel Error is defined as the total error measured compared to the ideal value. Total Channel Error is the sum of gain error and offset error combined. Figure 2-68 shows how Total Channel Error is measured.

Total Channel Error is defined as the difference between the actual ADC output and ideal ADC output. In the example shown in Figure 2-68, the Total Channel Error would be a negative number.

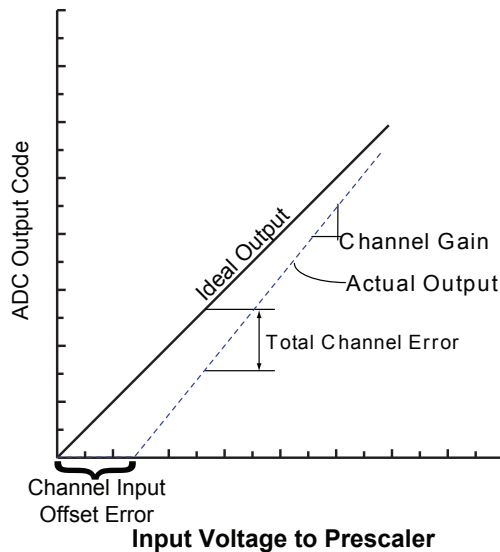


Figure 2-68 • Total Channel Error Example

Analog Quad ACM Description

Table 2-56 maps out the ACM space associated with configuration of the Analog Quads within the Analog Block. Table 2-56 shows the byte assignment within each quad and the function of each bit within each byte. Subsequent tables will explain each bit setting and how it corresponds to a particular configuration. After 3.3 V and 1.5 V are applied to Fusion, Analog Quad configuration registers are loaded with default settings until the initialization and configuration state machine changes them to user-defined settings.

Table 2-56 • Analog Quad ACM Byte Assignment

Byte	Bit	Signal (Bx)	Function	Default Setting
Byte 0 (AV)	0	B0[0]	Scaling factor control – prescaler	Highest voltage range
	1	B0[1]		
	2	B0[2]		
	3	B0[3]	Analog MUX select	Prescaler
	4	B0[4]	Current monitor switch	Off
	5	B0[5]	Direct analog input switch	Off
	6	B0[6]	Selects V-pad polarity	Positive
	7	B0[7]	Prescaler op amp mode	Power-down
Byte 1 (AC)	0	B1[0]	Scaling factor control – prescaler	Highest voltage range
	1	B1[1]		
	2	B1[2]		
	3	B1[3]	Analog MUX select	Prescaler
	4	B1[4]		
	5	B1[5]	Direct analog input switch	Off
	6	B1[6]	Selects C-pad polarity	Positive
	7	B1[7]	Prescaler op amp mode	Power-down
Byte 2 (AG)	0	B2[0]	Internal chip temperature monitor *	Off
	1	B2[1]	Spare	–
	2	B2[2]	Current drive control	Lowest current
	3	B2[3]		
	4	B2[4]	Spare	–
	5	B2[5]	Spare	–
	6	B2[6]	Selects G-pad polarity	Positive
	7	B2[7]	Selects low/high drive	Low drive
Byte 3 (AT)	0	B3[0]	Scaling factor control – prescaler	Highest voltage range
	1	B3[1]		
	2	B3[2]		
	3	B3[3]	Analog MUX select	Prescaler
	4	B3[4]		
	5	B3[5]	Direct analog input switch	Off
	6	B3[6]	–	–
	7	B3[7]	Prescaler op amp mode	Power-down

Note: *For the internal temperature monitor to function, Bit 0 of Byte 2 for all 10 Quads must be set.

**Table 2-73 • Maximum I/O Frequency for Single-Ended, Voltage-Referenced, and Differential I/Os;
All I/O Bank Types (maximum drive strength and high slew selected)**

Specification	Performance Up To
LVTTL/LVCMOS 3.3 V	200 MHz
LVCMOS 2.5 V	250 MHz
LVCMOS 1.8 V	200 MHz
LVCMOS 1.5 V	130 MHz
PCI	200 MHz
PCI-X	200 MHz
HSTL-I	300 MHz
HSTL-II	300 MHz
SSTL2-I	300 MHz
SSTL2-II	300 MHz
SSTL3-I	300 MHz
SSTL3-II	300 MHz
GTL+ 3.3 V	300 MHz
GTL+ 2.5 V	300 MHz
GTL 3.3 V	300 MHz
GTL 2.5 V	300 MHz
LVDS	350 MHz
LVPECL	300 MHz

Table 2-77 • Comparison Table for 5 V–Compliant Receiver Scheme

Scheme	Board Components	Speed	Current Limitations
1	Two resistors	Low to high ¹	Limited by transmitter's drive strength
2	Resistor and Zener 3.3 V	Medium	Limited by transmitter's drive strength
3	Bus switch	High	N/A
4	Minimum resistor value ² R = 47 Ω at T _J = 70°C R = 150 Ω at T _J = 85°C R = 420 Ω at T _J = 100°C	Medium	Maximum diode current at 100% duty cycle, signal constantly at '1' 52.7 mA at T _J = 70°C / 10-year lifetime 16.5 mA at T _J = 85°C / 10-year lifetime 5.9 mA at T _J = 100°C / 10-year lifetime For duty cycles other than 100%, the currents can be increased by a factor = 1 / (duty cycle). Example: 20% duty cycle at 70°C Maximum current = (1 / 0.2) * 52.7 mA = 5 * 52.7 mA = 263.5 mA

Notes:

1. Speed and current consumption increase as the board resistance values decrease.
2. Resistor values ensure I/O diode long-term reliability.

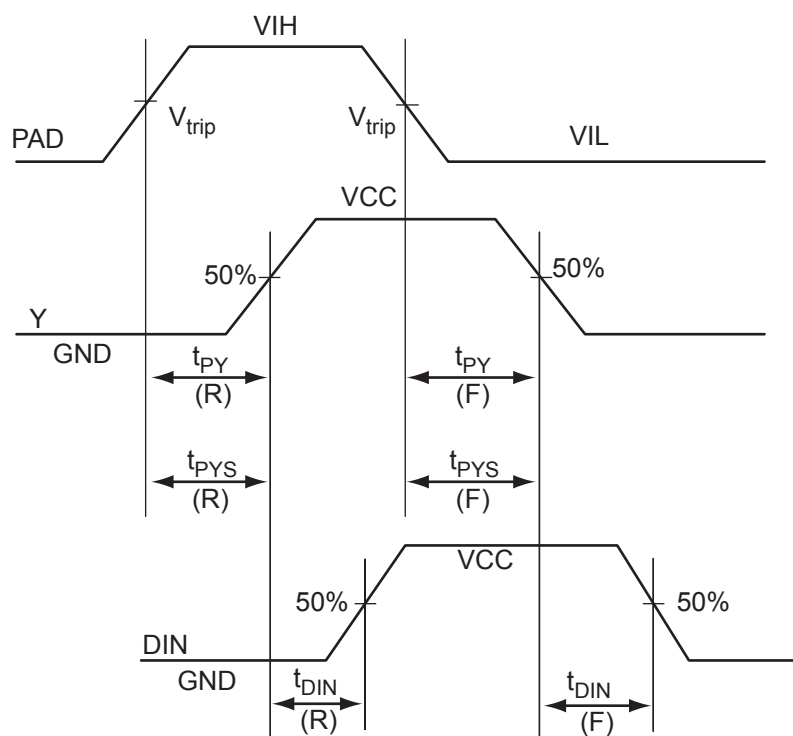
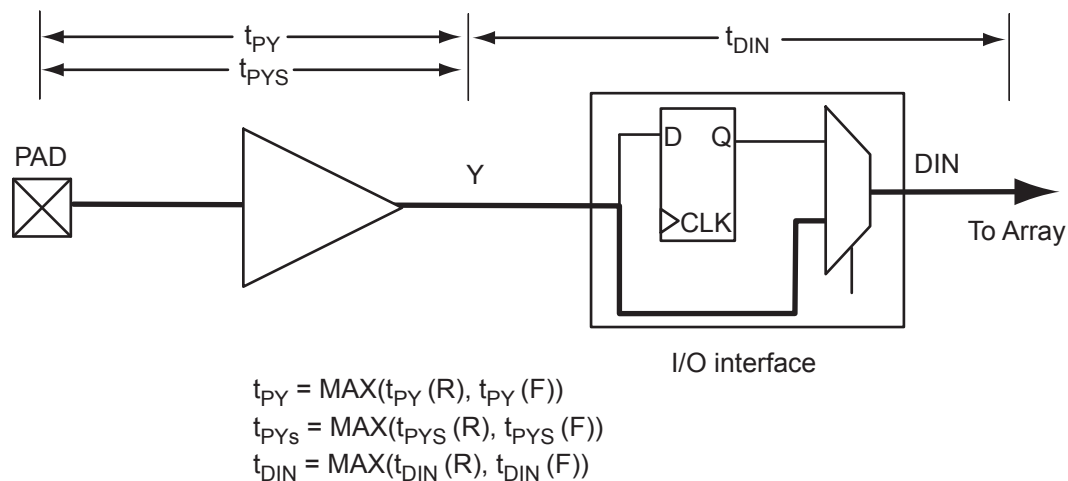


Figure 2-116 • Input Buffer Timing Model and Delays (example)

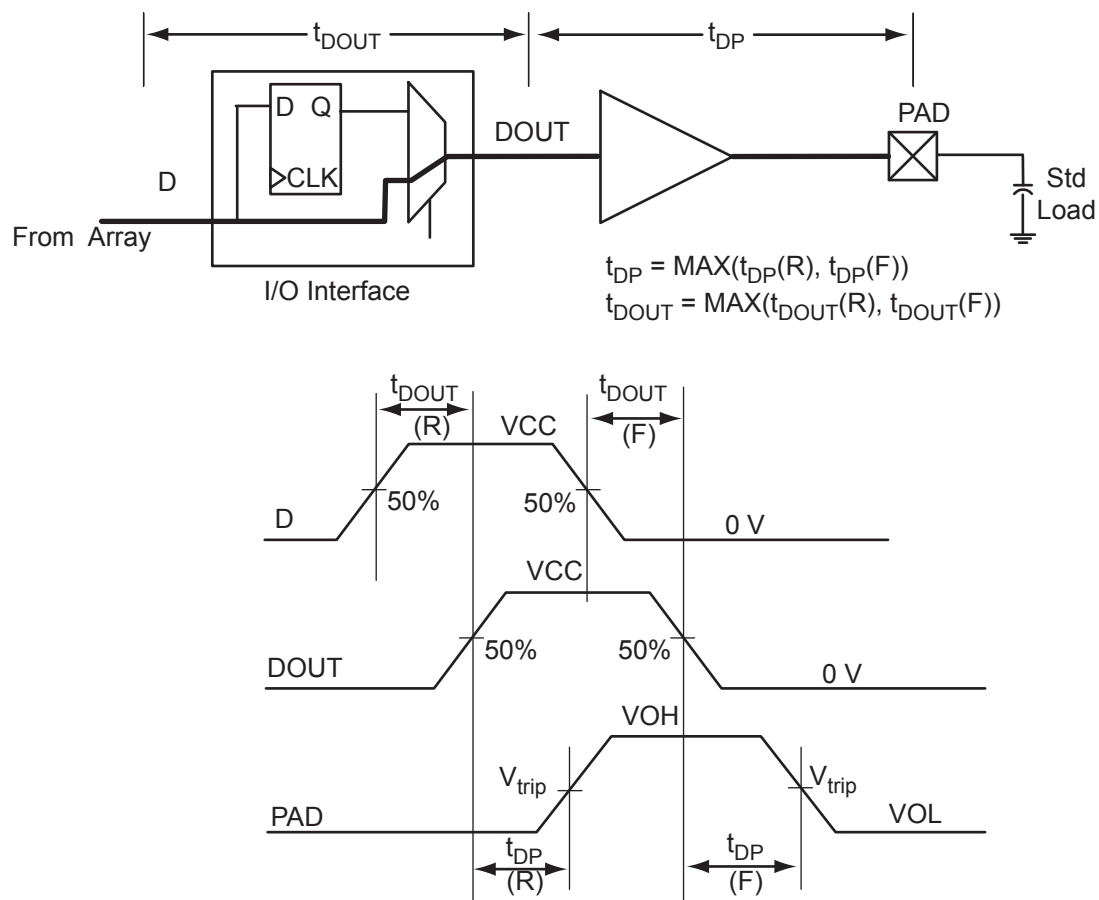


Figure 2-117 • Output Buffer Model and Delays (example)

Fully Registered I/O Buffers with Synchronous Enable and Asynchronous Clear

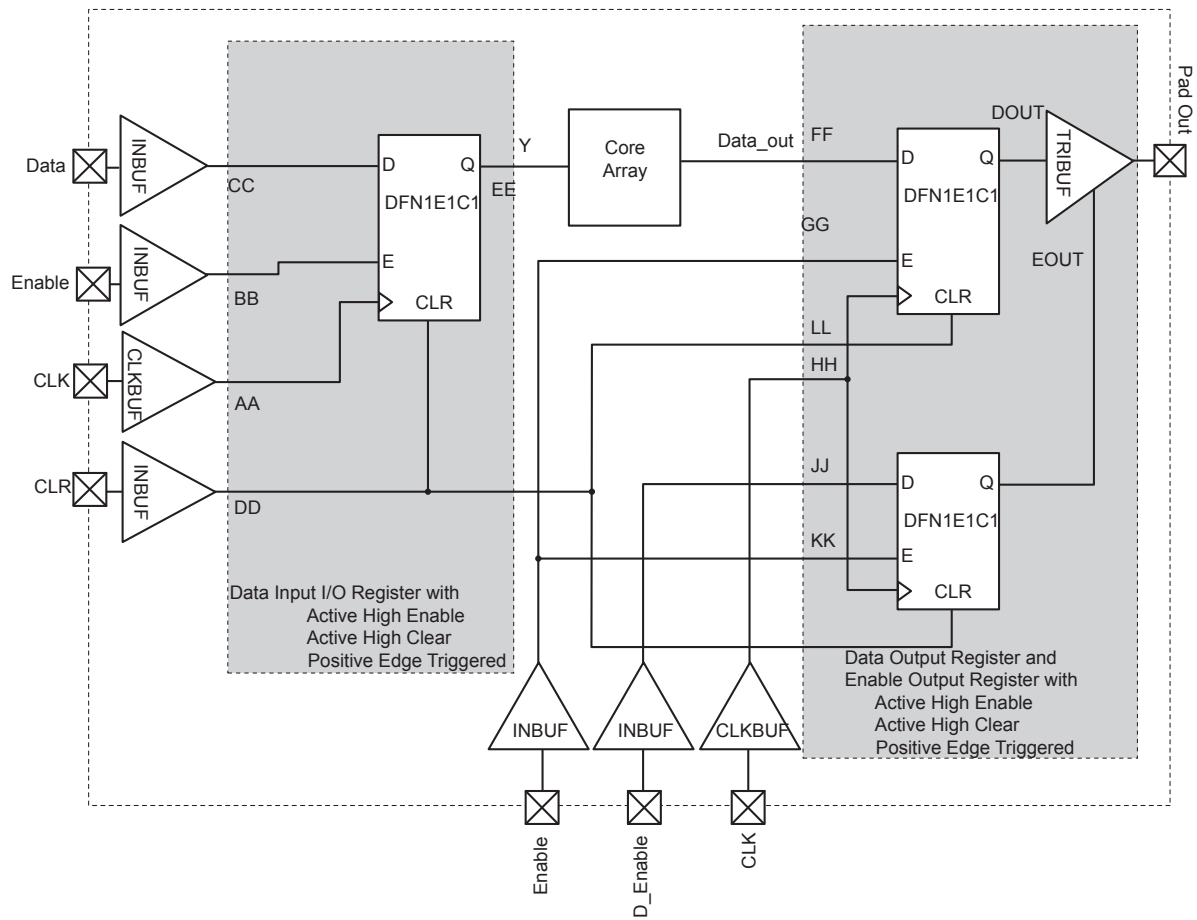


Figure 2-138 • Timing Model of the Registered I/O Buffers with Synchronous Enable and Asynchronous Clear

connected to the internal core logic I/O tile and the input, output, and control ports of an I/O buffer to capture and load data into the register to control or observe the logic state of each I/O.

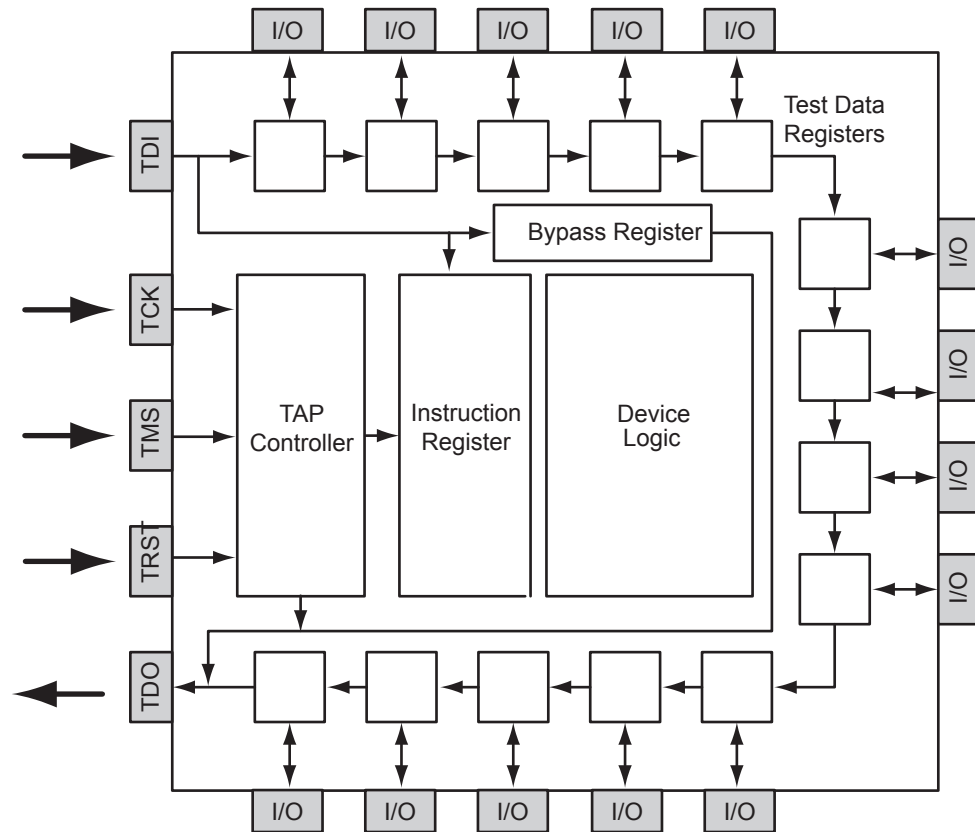


Figure 2-146 • Boundary Scan Chain in Fusion

Table 2-185 • Boundary Scan Opcodes

	Hex Opcode
EXTEST	00
HIGHZ	07
USERCODE	0E
SAMPLE/PRELOAD	01
IDCODE	0F
CLAMP	05
BYPASS	FF

Calculating Power Dissipation

Quiescent Supply Current

Table 3-8 • AFS1500 Quiescent Supply Current Characteristics

Parameter	Description	Conditions	Temp.	Min.	Typ.	Max.	Unit
ICC ¹	1.5 V quiescent current	Operational standby ⁴ , VCC = 1.575 V	T _J = 25°C		20	40	mA
			T _J = 85°C		32	65	mA
			T _J = 100°C		59	120	mA
		Standby mode ⁵ or Sleep mode ⁶ , VCC = 0 V			0	0	μA
ICC33 ²	3.3 V analog supplies current	Operational standby ⁴ , VCC33 = 3.63 V	T _J = 25°C		9.8	13	mA
			T _J = 85°C		10.7	14	mA
			T _J = 100°C		10.8	15	mA
		Operational standby, only Analog Quad and –3.3 V output ON, VCC33 = 3.63 V	T _J = 25°C		0.31	2	mA
			T _J = 85°C		0.35	2	mA
			T _J = 100°C		0.45	2	mA
		Standby mode ⁵ , VCC33 = 3.63 V	T _J = 25°C		2.9	3.6	mA
			T _J = 85°C		2.9	4	mA
			T _J = 100°C		3.3	6	mA
		Sleep mode ⁶ , VCC33 = 3.63 V	T _J = 25°C		17	19	μA
			T _J = 85°C		18	20	μA
			T _J = 100°C		24	25	μA
ICCI ³	I/O quiescent current	Operational standby ⁴ , Standby mode, and Sleep Mode ⁶ , VCCIx = 3.63 V	T _J = 25°C		417	649	μA
			T _J = 85°C		417	649	μA
			T _J = 100°C		417	649	μA

Notes:

1. ICC is the 1.5 V power supplies, ICC and ICC15A.
2. ICC33A includes ICC33A, ICC33PMP, and ICCOSC.
3. ICCI includes all ICCI0, ICCI1, ICCI2, and ICCI4.
4. Operational standby is when the Fusion device is powered up, all blocks are used, no I/O is toggling, Voltage Regulator is loaded with 200 mA, VCC33PMP is ON, XTAL is ON, and ADC is ON.
5. XTAL is configured as high gain, VCC = VJTAG = VPUMP = 0 V.
6. Sleep Mode, VCC = VJTAG = VPUMP = 0 V.

Total Static Power Consumption— P_{STAT}

Number of Quads used: $N_{QUADS} = 4$

Number of NVM blocks available (AFS600): $N_{NVM-BLOCKS} = 2$

Number of input pins used: $N_{INPUTS} = 30$

Number of output pins used: $N_{OUTPUTS} = 40$

Operating Mode

$$P_{STAT} = PDC1 + (N_{NVM-BLOCKS} * PDC4) + PDC5 + (N_{QUADS} * PDC6) + (N_{INPUTS} * PDC7) + (N_{OUTPUTS} * PDC8)$$

$$P_{STAT} = 7.50 \text{ mW} + (2 * 1.19 \text{ mW}) + 8.25 \text{ mW} + (4 * 3.30 \text{ mW}) + (30 * 0.00) + (40 * 0.00)$$

$$P_{STAT} = 31.33 \text{ mW}$$

Standby Mode

$$P_{STAT} = PDC2$$

$$P_{STAT} = 0.03 \text{ mW}$$

Sleep Mode

$$P_{STAT} = PDC3$$

$$P_{STAT} = 0.03 \text{ mW}$$

Total Power Consumption— P_{TOTAL}

In operating mode, the total power consumption of the device is 174.39 mW:

$$P_{TOTAL} = P_{STAT} + P_{DYN}$$

$$P_{TOTAL} = 143.06 \text{ mW} + 31.33 \text{ mW}$$

$$P_{TOTAL} = 174.39 \text{ mW}$$

In standby mode, the total power consumption of the device is limited to 0.66 mW:

$$P_{TOTAL} = P_{STAT} + P_{DYN}$$

$$P_{TOTAL} = 0.03 \text{ mW} + 0.63 \text{ mW}$$

$$P_{TOTAL} = 0.66 \text{ mW}$$

In sleep mode, the total power consumption of the device drops as low as 0.03 mW:

$$P_{TOTAL} = P_{STAT} + P_{DYN}$$

$$P_{TOTAL} = 0.03 \text{ mW}$$

FG484		
Pin Number	AFS600 Function	AFS1500 Function
H13	GND	GND
H14	VCCIB1	VCCIB1
H15	GND	GND
H16	GND	GND
H17	NC	IO53NDB2V0
H18	IO38PDB2V0	IO57PDB2V0
H19	GCA2/IO39PDB2V0	GCA2/IO59PDB2V0
H20	VCCIB2	VCCIB2
H21	IO37NDB2V0	IO54NDB2V0
H22	IO37PDB2V0	IO54PDB2V0
J1	NC	IO112PPB4V0
J2	IO76NDB4V0	IO113NDB4V0
J3	GFB2/IO74PDB4V0	GFB2/IO109PDB4V0
J4	GFA2/IO75PDB4V0	GFA2/IO110PDB4V0
J5	NC	IO112NPB4V0
J6	NC	IO104PDB4V0
J7	NC	IO111PDB4V0
J8	VCCIB4	VCCIB4
J9	GND	GND
J10	VCC	VCC
J11	GND	GND
J12	VCC	VCC
J13	GND	GND
J14	VCC	VCC
J15	VCCIB2	VCCIB2
J16	GCB2/IO40PDB2V0	GCB2/IO60PDB2V0
J17	NC	IO58NDB2V0
J18	IO38NDB2V0	IO57NDB2V0
J19	IO39NDB2V0	IO59NDB2V0
J20	GCC2/IO41PDB2V0	GCC2/IO61PDB2V0
J21	NC	IO55PSB2V0
J22	IO42PDB2V0	IO56PDB2V0
K1	GFC2/IO73PDB4V0	GFC2/IO108PDB4V0
K2	GND	GND
K3	IO74NDB4V0	IO109NDB4V0

FG484		
Pin Number	AFS600 Function	AFS1500 Function
K4	IO75NDB4V0	IO110NDB4V0
K5	GND	GND
K6	NC	IO104NDB4V0
K7	NC	IO111NDB4V0
K8	GND	GND
K9	VCC	VCC
K10	GND	GND
K11	VCC	VCC
K12	GND	GND
K13	VCC	VCC
K14	GND	GND
K15	GND	GND
K16	IO40NDB2V0	IO60NDB2V0
K17	NC	IO58PDB2V0
K18	GND	GND
K19	NC	IO68NPB2V0
K20	IO41NDB2V0	IO61NDB2V0
K21	GND	GND
K22	IO42NDB2V0	IO56NDB2V0
L1	IO73NDB4V0	IO108NDB4V0
L2	VCCOSC	VCCOSC
L3	VCCIB4	VCCIB4
L4	XTAL2	XTAL2
L5	GFC1/IO72PDB4V0	GFC1/IO107PDB4V0
L6	VCCIB4	VCCIB4
L7	GFB1/IO71PDB4V0	GFB1/IO106PDB4V0
L8	VCCIB4	VCCIB4
L9	GND	GND
L10	VCC	VCC
L11	GND	GND
L12	VCC	VCC
L13	GND	GND
L14	VCC	VCC
L15	VCCIB2	VCCIB2
L16	IO48PDB2V0	IO70PDB2V0

FG676	
Pin Number	AFS1500 Function
R21	IO72NDB2V0
R22	IO72PDB2V0
R23	GND
R24	IO71PDB2V0
R25	VCCIB2
R26	IO67NDB2V0
T1	GND
T2	NC
T3	GFA1/IO105PDB4V0
T4	GFA0/IO105NDB4V0
T5	IO101NDB4V0
T6	IO96PDB4V0
T7	IO96NDB4V0
T8	IO99NDB4V0
T9	IO97NDB4V0
T10	VCCIB4
T11	VCC
T12	GND
T13	VCC
T14	GND
T15	VCC
T16	GND
T17	VCCIB2
T18	IO83NDB2V0
T19	IO78NDB2V0
T20	GDA1/IO81PDB2V0
T21	GDB1/IO80PDB2V0
T22	IO73NDB2V0
T23	IO73PDB2V0
T24	IO71NDB2V0
T25	NC
T26	GND
U1	NC
U2	NC
U3	IO102PDB4V0
U4	IO102NDB4V0

FG676	
Pin Number	AFS1500 Function
U5	VCCIB4
U6	IO91PDB4V0
U7	IO91NDB4V0
U8	IO92PDB4V0
U9	GND
U10	GND
U11	VCC33A
U12	GNDA
U13	VCC33A
U14	GNDA
U15	VCC33A
U16	GNDA
U17	VCC
U18	GND
U19	IO74NDB2V0
U20	GDA0/IO81NDB2V0
U21	GDB0/IO80NDB2V0
U22	VCCIB2
U23	IO75NDB2V0
U24	IO75PDB2V0
U25	NC
U26	NC
V1	NC
V2	VCCIB4
V3	IO100PPB4V0
V4	GND
V5	IO95PDB4V0
V6	IO95NDB4V0
V7	VCCIB4
V8	IO92NDB4V0
V9	GNDNVM
V10	GNDA
V11	NC
V12	AV4
V13	NC
V14	AV5

FG676	
Pin Number	AFS1500 Function
V15	AC5
V16	NC
V17	GNDA
V18	IO77PPB2V0
V19	IO74PDB2V0
V20	VCCIB2
V21	IO82NDB2V0
V22	GDA2/IO82PDB2V0
V23	GND
V24	GDC1/IO79PDB2V0
V25	VCCIB2
V26	NC
W1	GND
W2	IO94PPB4V0
W3	IO98PDB4V0
W4	IO98NDB4V0
W5	GEC1/IO90PDB4V0
W6	GEC0/IO90NDB4V0
W7	GND
W8	VCCNVM
W9	VCCIB4
W10	VCC15A
W11	GNDA
W12	AC4
W13	VCC33A
W14	GNDA
W15	AG5
W16	GNDA
W17	PUB
W18	VCCIB2
W19	TDI
W20	GND
W21	IO84NDB2V0
W22	GDC2/IO84PDB2V0
W23	IO77NPB2V0
W24	GDC0/IO79NDB2V0